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FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
11/24/2003	Shinji Ohuchi	OKI.136D3	1262
7590 06/16/2005		EXAMINER	
VOLENTINE FRANCOS, & WHITT PLLC		PERALTA, GINETTE	
•	260	ARTINIT	PAPER NUMBER
RESTON, VA 20190			TALER NOMBER
	11/24/2003 7590 06/16/2005 INE FRANCOS, & WEDOM SQUARE EDOM DRIVE SUITE I	11/24/2003 Shinji Ohuchi 7590 06/16/2005 INE FRANCOS, & WHITT PLLC EDOM SQUARE EDOM DRIVE SUITE 1260	11/24/2003 Shinji Ohuchi OKI.136D3 7590 06/16/2005 EXAM INE FRANCOS, & WHITT PLLC EDOM SQUARE EDOM DRIVE SUITE 1260 ART UNIT

DATE MAILED: 06/16/2005

Please find below and/or attached an Office communication concerning this application or proceeding.

			AK_
	Application No.	Applicant(s)	
	10/718,549	OHUCHI ET AL.	
Office Action Summary	Examiner	Art Unit	
	Ginette Peralta	2814	
The MAILING DATE of this communication apperiod for Reply	ppears on the cover sheet w	ith the correspondence addre	ss
A SHORTENED STATUTORY PERIOD FOR REP THE MAILING DATE OF THIS COMMUNICATION - Extensions of time may be available under the provisions of 37 CFR 1 after SIX (6) MONTHS from the mailing date of this communication. - If the period for reply specified above is less than thirty (30) days, a re - If NO period for reply is specified above, the maximum statutory perio - Failure to reply within the set or extended period for reply will, by statu Any reply received by the Office later than three months after the mail earned patent term adjustment. See 37 CFR 1.704(b).	1. 1.136(a). In no event, however, may a eply within the statutory minimum of thind will apply and will expire SIX (6) MOI ute, cause the application to become Al	reply be timely filed ty (30) days will be considered timely. NTHS from the mailing date of this commi	unication.
Status			
1) Responsive to communication(s) filed on			
·— · · —	nis action is non-final.		
3) Since this application is in condition for allow	vance except for formal mat	ters, prosecution as to the me	erits is
closed in accordance with the practice under	r <i>Ex parte</i> Q <i>uayle</i> , 1935 C.[). 11, 453 O.G. 213.	
Disposition of Claims			
4) ⊠ Claim(s) 10-17 is/are pending in the applicat 4a) Of the above claim(s) is/are withdown 5) □ Claim(s) is/are allowed. 6) ⊠ Claim(s) 10-17 is/are rejected. 7) □ Claim(s) is/are objected to. 8) □ Claim(s) are subject to restriction and	rawn from consideration.		
Application Papers			
9) The specification is objected to by the Examination The drawing(s) filed on is/are: a) and applicant may not request that any objection to the Replacement drawing sheet(s) including the correction. 11) The oath or declaration is objected to by the	ccepted or b) objected to ne drawing(s) be held in abeya ection is required if the drawing	nce. See 37 CFR 1.85(a). g(s) is objected to. See 37 CFR 1	
Priority under 35 U.S.C. § 119			
12) △ Acknowledgment is made of a claim for foreign a) △ All b) ☐ Some * c) ☐ None of: 1. ☐ Certified copies of the priority docume 2. △ Certified copies of the priority docume 3. ☐ Copies of the certified copies of the prapplication from the International Bure * See the attached detailed Office action for a li	ents have been received. ents have been received in a riority documents have been eau (PCT Rule 17.2(a)).	Application No. <u>09/460,987</u> . n received in this National Sta	age
Attachment(s) 1) Notice of References Cited (PTO-892) 2) Notice of Draftsperson's Patent Drawing Review (PTO-948) 3) Information Disclosure Statement(s) (PTO-1449 or PTO/SB/0 Paper No(s)/Mail Date 11/24/03.	Paper No	Summary (PTO-413) (s)/Mail Date Informal Patent Application (PTO-15 	i2)

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DETAILED ACTION

Claim Rejections - 35 USC § 103

- 1. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:
 - (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.
- 2. Claim Prejected under 35 U.S.C. 103(a) as being unpatentable over Capote et al. (U. S. Pat. 6,297,560 B1) in view of Riding et al. (U. S. Pat. 6.083,811).

Regarding claim 10, Capote et al. discloses a method of mounting a semiconductor device on a mounting substrate that comprises providing the semiconductor device as including a semiconductor element 10, a sealing resin (22 or 37), and a plurality of terminals 14; the semiconductor element having a thickness, a first surface wherein circuitry 24 is formed, a second surface, and side surfaces positioned between the first and second surfaces, the sealing resin (22, 37) having a thickness between about 50 microns and 200 microns (as disclosed in col. 6, lines 40-41) so that the second and side surfaces are not sealed by the sealing resin (22, 37), each of the plurality of terminals 14 being electrically connected to the circuitry 24; putting the semiconductor device on a mounting substrate 20, so that the first surface of the semiconductor device faces the mounting substrate; and fixing the semiconductor

device on the mounting substrate 20 by a heat treatment (as disclosed in col. 7, lines 1-16).

Capote et al. discloses the claimed invention with the exception of disclosing the thickness of the semiconductor element, and the thickness of the sealing resin in relation to the thickness of the semiconductor element.

Riding et al. discloses a method of mounting a semiconductor device on a mounting substrate that comprises providing a semiconductor device 12 as including a semiconductor element 20 and a sealing resin 22 (as disclosed in col. 4, lines 1-29); the semiconductor element having a thickness of 200 µ or less (as disclosed in col. 4, lines 10-12, wherein the dice has a thickness of 4 mils \approx 102 μ), a first surface wherein circuitry is formed, a second surface, and side surfaces positioned between the first and second surfaces, the sealing resin not sealing the second and side surfaces; putting the semiconductor device 12 on a mounting substrate 22, so that the first surface of the semiconductor device faces the mounting substrate, wherein the thickness of the semiconductor element being 200 μ or less is taught for the well known and intended purpose of teaching the miniaturization which is ever occurring in the semiconductor devices and manufacturing field, and thus shows that using a semiconductor element of 200 μ or less would be within the scope of one of ordinary skill in the art.

Thus, it would have been obvious to one of ordinary skill in the art at the time the invention was made that the semiconductor element of Capote et al. could have a thickness of 200 µ or less, and furthermore that since Capote et al. discloses that the

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thickness of the sealing resin ranges from 50 to 200 μ , that the sealing resin could have a thickness equal to or greater than half a thickness of the semiconductor element. Furthermore, it would have been obvious to one of ordinary skill in the art at the time the invention was made to use a semiconductor element having any desired thickness

as there is no statement denoting the criticality of the semiconductor element thickness.

"In the case where the claimed ranges "overlap or lie inside ranges disclosed by the prior art" a prima facie case of obviousness exists. In re Wertheim, 541 F.2d 257, 191 USPQ 90 (CCPA 1976); In re Woodruff, 919 F.2d 1575, 16 USPQ2d 1934 (Fed. Cir. 1990) (The prior art taught carbon monoxide concentrations of "about 1-5%" while the claim was limited to "more than 5%." The court held that "about 1-5%" allowed for concentrations slightly above 5% thus the ranges overlapped.)" (MPEP 2144.04)

Regarding claim 11, Capote et al. discloses that the semiconductor element has a central portion and a peripheral portion surrounding the central portion, the peripheral portion having a step part, wherein a thickness of the sealing resin (22, 37) on the step part is greater than a thickness of the sealing resin on the central portion.

Regarding claims 12, and 13, Capote et al. discloses that the mounting substrate may be a printing board (as disclosed in col. 1, lines 63-67).

Regarding claims 14, 15, 16, and 17, Capote et al. discloses that the plurality of terminals are solder balls 14, the heat treatment comprises reflow of solder balls 14.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Ginette Peralta whose telephone number is (571) 272-1713. The examiner can normally be reached on Monday to Friday 8:00 AM- 5:30 PM.

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If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Wael Fahmy can be reached on (571) 272-1705. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

GP

LONG PHAM
RIMARY EXAMINER